

## BOARD-TO-BOARD CONNECTORS IN HIGH-SPEED SIGNAL CHAINS

WURTH ELEKTRONIK MORE THAN YOU EXPECT

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Required concepts for understanding





#### Electronic System Architecture

- In a electronic system, a computing chip (either a microcontroller, a microprocessor or system-on-chip) will be **processing** what it gets from its system bus.
- The system bus links to the memory controller, which handle the system's communication with the memory
- Downstream of the system bus, a I/O controller will handle all the inputs and outputs of the system
- I/O protocols don't necessarily involve an external connector on the device
- Some protocols can either be on the memory or the I/O controller



Parallel and Serial Transmission

- Serial
  - Symbols are transmitted over 1 channel in sequence

8, 7, 6, 5, 4, 3, 2, 1

- 1 channel = 1 or 2 wires
- Parallel
  - Symbols are transmitted over n channels, then put again into a sequence
  - The number of channels n is referrend as the « bit width »





Limits of Transmission

- The recieving chip has to be able to read the symbol
  - Symbol = voltage level or transition
- Sample Rate = the frequency of the reading in the recieving device
  - In Transfers/second (T/s)
- Losses are frequency-dependant



Figure 2. Single pulse response of a DQ line shows both frequency-dependent loss and reflections in a DDR5 channel.



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Frequency Channel Losses

- Signal loss at high frequency comes from :
  - Impedance
  - Impedance mismatch
  - Signal going to nearby conductors : Crosstalk

#### ➔ Connectors and cables are a source of high-frequency losses





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#### **Reflection Coefficient**



Transmission Coefficient

$$\tau = 1 - \frac{Z_{CAB} - Z_S}{Z_{CAB} + Z_S}$$



#### Impedance matching

- Minimizes signal reflections
- Maximizes efficiency

#### Transmission line in connectors

- To limit losses in connectors, impedance must be matched with PCB
  - Pins on connector ends have a different impedance, it is unadvised to use them for signal
    - It is not always possible (see RJ45)
  - Best performance is reached when signal pins have ground pins around them



Nyquist Frequency

 Shannon's theorem states that a periodic signal must be sampled at more than twice the highest frequency component of the signal to keep information integrity

•  $f_{max,signal} = \frac{Sample Rate}{2}$ 

- Protocols can specify a channel loss at *f<sub>max,signal</sub>*, called the Nyquist Frequency
  - ➔ To see if a connector technology, you have to check the allowed Insertion Loss at the f<sub>Nyquist</sub>



1



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Sampling



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Sample Rate : 1/T

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Example : Category Rating for Ethernet Physical Layer

- Example in the industry : Ethernet cabling
  - Every component (Modular Jacks, Cable...) has an allowed loss budget in dB
    - 1,5 dB loss is 29% of the signal lost
    - 3 dB loss is half of the signal lost
  - You can add the losses of the components on the signal chain
- **>** Standards : Physical Layers



## EIA 568 standard insertion losses for Ethernet Jacks as a

# <u>CONNECTORS FOR</u> <u>MEMORY SIGNAL CHAINS</u>

Northbridge/Memory Bus





#### **DRAM** Connectors

- Dynamic Random-Access Memory (as opposed to Static RAM embedded in chips)
- Used by systems to store data and programs while in use
- Widespread technology : DDR SDRAM
  - Double Data Rate Synchronous Dynamic Random-Access Memory
  - **Standardized chips** and modules treated like commodities
  - Standard maintained by the JEDEC
  - Levels of standard from DDR (1) to DDR5
  - Available in higher bandwidth for video memory (GDDR)
- Parallel Transmission (GSG configuration)
- Nyquist Frequency from 100MHz (DDR) to 3,6GHz (DDR5)





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|                                |                |                 |                       | _                |                       |                        | _   |         |
|--------------------------------|----------------|-----------------|-----------------------|------------------|-----------------------|------------------------|---|---------|
| Spot Memory Card               |                | SSD Contract    |                       | M                | odile DRA             | M e                    | eMMC  |         |
| DRAM Spot Price MORE           |                | L               | ast Up                | date: Sep.       | 28 2023 1             | 8:10 (GMT              | (+8) <price< th=""><th>Notice&gt;</th></price<> | Notice> |
| Early notice was announ        | ced at :       | 17:50.<br>Daily | <u>(20 n</u><br>Daily | v Sessior        | n advano<br>n Session | <u>ce)</u><br>Session  | Session   |         |
| Item                           |                | High            | Low                   | High             | Low                   | Average                | Change  | History |
| DDR4 16Gb (1Gx16)3200          |                | 3.45            | 2.68                  | 3.45             | 2.68                  | 2.996                  | 0.98 %  | ~~      |
| 🖬 DDR4 16Gb (2Gx8)3200         |                | 3.35            | 2.65                  | 3.35             | 2.65                  | 2.934                  | <b>0</b> .21 %                                  | ~~      |
| 🖪 DDR4 8Gb (1Gx8) 3200         |                | 1.65            | 1.37                  | 1.65             | 1.37                  | 1.450                  | 0.00 %  | ~~      |
| DDR4 8Gb (512Mx16) 3200        |                | 1.75            | 1.42                  | 1.75             | 1.42                  | 1.502                  | 0.00 %  | ~~      |
| 🖪 DDR4 8Gb (1Gx8) eTT          |                | 1.27 1.03       |                       | 1.27             | 1.03                  | 1.152                  | <b>6</b> 0.17 %                                 | ~~      |
| DDR3 4Gb 512Mx8 1600           | /1866          | SK Hy           | nix, N                | Micron, S        | Samsung               | g, Nanya               | 0.00 %  | ~       |
| Module Spot Price MORE         |                |                 | Last Up               | odate:Sep.       | 18 2023 1             | 4:40 (GM1              | (+8) <price< td=""><td>Notice&gt;</td></price<> | Notice> |
| Item                           | Weekly<br>High | / Wee           | ekly :<br>w           | Session<br>High  | Session<br>Low        | Session<br>Average     | Average<br>Change                               | History |
| M DDR4 SODIMM 8GB<br>2666      | 15.70          | 11.             | .60                   | 15.70            | 11.60                 | 13.856                 | 0.93 %  | ~       |
| DDR4 UDIMM 8GB 2666            | 15.20          | 11.             | .60                   | 15.20            | 11.60                 | 13.684                 | <b>4</b><br>2.55 %                              | ~~~     |
| DDR4 RDIMM 16GB                | 38.50          | 37.             | .00                   | 38.50            | 37.00                 | 37.500                 | ▲<br>3.59 %                                     |         |
| Flash Spot Price MORE          |                | L               | .ast Up               | date: Sep.       | 28 2023 1             | 8:10 (GMT              | (+8) <price< td=""><td>Notice&gt;</td></price<> | Notice> |
| <u>Early notice was announ</u> | ced at :       | 17:50.          | ( <u>20 n</u>         | <u>ninutes i</u> | n advano              | <u>ce</u> )<br>Seccion | Section   |         |
| Item                           |                | High            | Low                   | High             | Low                   | Average                | Change  | History |
| SLC 2Gb 256MBx8                |                | 1.25            | 0.56                  | 1.25             | 0.56                  | 0.771                  | -0.52 %   | ~~      |
| SLC 1Gb 128MBx8                |                | 1.65            | 0.52                  | 1.65             | 0.52                  | 0.812                  | ▲<br>0.37 %                                     | ~~      |
| MLC 64Gb 8GBx8                 |                | 4.25            | 3.40                  | 4.25             | 3.40                  | 3.867                  | 0.00 %  | ~~      |
| MLC 32Gb 4GBx8                 |                | 3.00            | 1.90                  | 3.00             | 1.90                  | 2.063                  | 0.00 %  | ~~      |
| GDDR Spot Price MORE           |                |                 | Last Up               | odate:Sep.       | 18 2023 1             | 4:40 (GMT              | (+8) <price< td=""><td>Notice&gt;</td></price<> | Notice> |
| Item                           | Weekly<br>High | / Wee           | ekly ∷<br>ow          | Session<br>High  | Session<br>Low        | Session<br>Average     | Average<br>Change                               | History |
| GDDR5 8Gb                      | 4.20           | 3.4             | 40                    | 4.20             | 3.40                  | 3.649                  | <b>4</b> .62 %                                  | ~       |
| GDDR6 8Gb                      | 3.50           | 2.              | 10                    | 3.50             | 2.10                  | 2.957                  | ▲<br>0.72 %                                     | ~       |
| LPDDR Spot Price MORE          | _              | L               | ast Up                | date: Sep.       | 18 2023 1             | 4:40 (GM1              | (+8) <price< td=""><td>Notice&gt;</td></price<> | Notice> |
| LPDDR 3 32Gb                   | 8              | LPDDR           | 3 160                 | Gb               | 8                     | LPDDR 3                | 8Gb   |         |
| LPDDR 4 32Gb                   | B              | LPDDR           | 4 160                 | Gb               | 8                     | LPDDR 4                | 8Gb   |         |

PCI Express

- Used for **chip-to-chip** communication at high speed
- Widespread Technology
  - Power and Data delivery Standard
  - Standard maintained by the PCI-SIG
  - Levels of standard available from PCIe 1 to PCIe 7
  - Available with 1 to 16 transmission/reception line
- Serial Transmission in GSSG differential configuration
- Nyquist Frequency from 1,2GHz (PCIe 1) to 32GHz (PCIe 7)

| tible to meet needs from handheld<br>ax Total Bandwidth = Max RX bandw<br>Permutations yielding 11 unique ba<br>oding overhead and header efficien | /client to server/HP<br>idth + Max TX bandw<br>ndwidth profiles<br>cy not included | C<br>ridth |             | ()<br>()<br>() | P        |                  |
|--|--|------------|-------------|----------------|----------|------------------|
| Specifications   | x1   | x2         | Lanes<br>x4 | x8             | x16      |                  |
| 2.5 GT/s (PCle 1.x +)  | 500 MB/S   | 1 GB/S     | 2 GB/S      | 4 GB/S         | 8 GB/S   | $\left  \right $ |
| 5.0 GT/s (PCle 2.x +)  | 1 GB/S   | 2 GB/S     | 4 GB/S      | 8 GB/S         | 16 GB/S  |                  |
| 8.0 GT/s (PCle 3.x +)  | 2 GB/S   | 4 GB/S     | 8 GB/S      | 16 GB/S        | 32 GB/S  |                  |
| 16.0 GT/s (PCle 4.x +)   | 4 GB/S   | 8 GB/S     | 16 GB/S     | 32 GB/S        | 64 GB/S  |                  |
| 32.0 GT/s (PCle 5.x +)   | 8 GB/S   | 16 GB/S    | 32 GB/S     | 64 GB/S        |          | ٩                |
| 64.0 GT/s (PCle 6.x +)   | 16 GB/S  | 32 GB/S    | 64 GB/S     |                | 256 GB/S |                  |
| 128.0 GT/s (PCle 7.x +)  | 32 GB/S  | 64 GB/S    | 128 GB/S    | 256 GB/S       | 512 GB/S |                  |



DDR SDRAM and PCI Express Standard Connectors

- Board Edge Connector
  - A counterpart PCB makes the connection
  - Very low losses at high frequency
  - Very bulky, only adapted for desktop PC and servers
- DIMM Connector
  - 150-200 contacts
  - DIMM : Dual Inline Memory Module
  - Different variants for each DDR level (notches)
- PCI Express connector
  - 36 contacts for PCIe x1
  - 64 contacts for PCIe x4
  - 98 contacts for PCIe x8
  - 164 contacts for PCIe x16
  - Physically compatible will all levels of PCIe



PCIe x4

PCle x16

PCle x1

#### DDR SDRAM and PCIe

- Alternative : Using Mezzanine Board-to-Board Connector is possible, however the standards are very demanding
  - 1,5 dB allowed losses GSSG at Nyquist in PCIe standard









Mezzanine Board-to-Board connectors

- WE **BTB08 and BTB1** series are well-suited for such applications
  - 100 Ohm Differential Impedance (as PCIe)
  - More compact than Board Edge Connectors
  - Limited insertion loss in GSSG configuration
  - Cross reference with TE and Amphenol (BTB08) and Molex (BTB1)
- However
  - Non-standard (limits interchangeability)
  - Lower power allowed than Board Edge Connectors



# <u>CONNECTORS FOR</u> I/O SIGNAL CHAINS

Southbridge/I/O





- Ethernet has a very complex signal chain
  - An internal interface has to be used to bring signal to the MAC (here, PCIe)
  - MII : internal universal interface to link the MAC to the PHY (the PHY can be optical or electrical)
  - MDI : external signal that goes in the Modular Jack and cable





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  - MDI : external signal that goes in the Modular Jack and cable



- Ethernet has a very complex signal chain
  - MDI : external signal that goes in the Modular Jack and cable
    - Active PHYciever
    - PCB trace
    - Passive Filters
    - Modular Jack
    - Cable with modular plugs
    - Modular Jack
    - Passive Filters
    - PCB trace
    - Active PHYciever



- Customer example
  - PHY and RJ45 not on the same PCB
  - 100BASE-T (Cat 5)
  - How to link both ?



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- But how ?





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- → Use a FFC with FPC connectors !
- But how ?
  - Use GSSG configuration
  - At least 13 pins
  - Not over 5-10cm
  - 100Ω differential impedance
- But isn't there a problem with Ethernet standard?



| Pin | Signal               |
|-----|----------------------|
| 1   | Ground               |
| 2   | Line from RJ45 pin 1 |
| 3   | Line from RJ45 pin 2 |
| 4   | Ground               |
| 5   | Line from RJ45 pin 3 |
| 6   | Line from RJ45 pin 6 |
| 7   | Ground               |
| 8   | Line from RJ45 pin 4 |
| 9   | Line from RJ45 pin 5 |
| 10  | Ground               |
| 11  | Line from RJ45 pin 7 |
| 12  | Line from RJ45 pin 8 |
| 13  | Ground               |



- Customer example
  - PHY and RJ45 not on the same PCB
  - 100BASE-T (Cat 5)
  - How to link both ?
- → Use a FFC with FPC connectors !
- But how ?
  - Use GSSG configuration
  - At least 13 pins
  - Not over 5-10cm
  - 100Ω differential impedance
- But isn't there a problem with Ethernet standard?
  Use a RJ45 one category higher ! (Cat 6)



USB HSIC

- USB can be used as a serial Board-to-Board communication protocol
  - Up to 2 high-speed lanes for transmission and reception in GSSG
  - Nyquist Frequency from 2.5 to 10 GHz for SuperSpeed
  - Total allowed losses : 24,5dB



Serial I/O Buses

- Serial bus SATA
  - Generally for internal uses only
  - One transmission line, one reception line
  - Flat cable with GSSG strips
  - Nyquist Frequency from 1,5 to 6GHz
- High speed serial I/O buses can use BTB connectors

#### I2C

- 5 to 2500 kHz Nyquist Frequency
- Most used :
  - 10kB/s (standard mode)
  - 400kB/s (fast mode)
- Used in a lot of other protocols for inter-chip communication
  - HDMI VGA, DVI, DIMMs, PCI, PCI Express
- Low-speed serial I/O buses can use pin and socket headers







Parallel I/O Buses

- IDE/PATA
  - 16 bits wide
  - Sample rate 80MT/s max
  - Bandwidth 1Gb/s max
  - 40-wire Ribbon Flat cable with 40-pins Box Headers

#### CompactFlash/PCMCIA

- 16 bits wide
- Sample rate up to 12,5Mt/s (PCMCIA), up to 80MT/s (CF)
- Bandwidth up to 200Mb/s (PCMCIA), up to 1,3Gb/s (CF)
- 50-pin or 68-pin Card Connector



## **CONCLUSION**





### **CONCLUSION**

- Signal chain analysis is going from the core of the system and analyzing the different protocols in place
- For us, signal chain analysis is :
  - How to find out which connectors customer may need to propose new solutions to customers.
  - A framework to **adapt our qualification tests** to give the most accurate information to the customers.
  - A good way to integrate work with our colleagues.
- It's always interesting to know and understand the environment in order to propose suitable solutions.







We are here for you now! Ask us directly via our chat or via E-Mail.

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